Mass fabrication and delivery of 3D multilayer μTags into living cells

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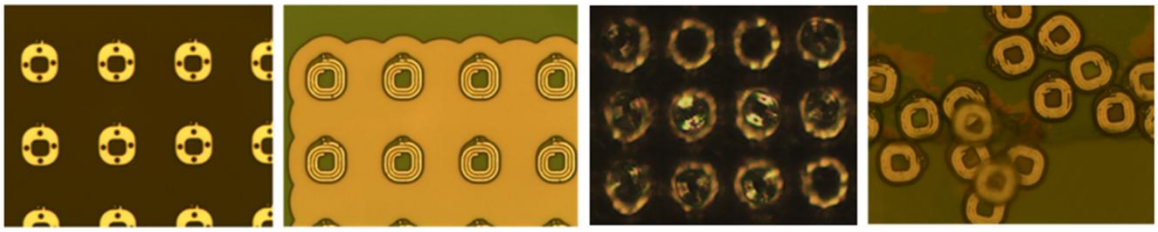
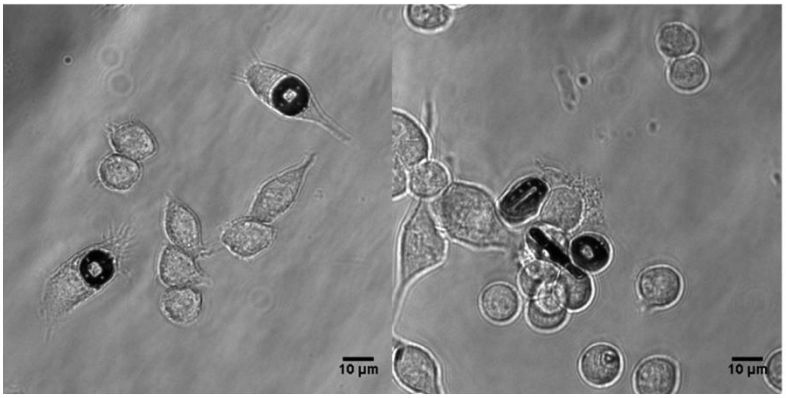
Supplementary Information



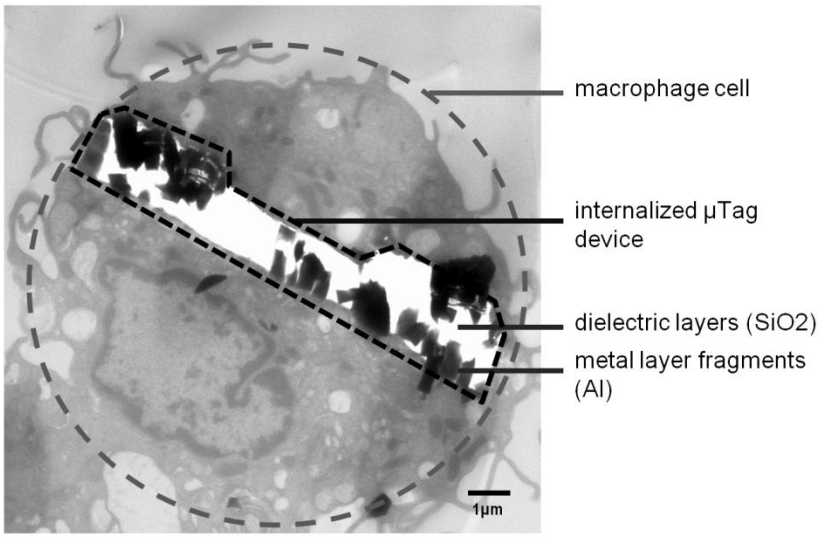
Supplementary Figure S1. Optical microscopy images of wafer after (a) first capacitance layer, (b) top oxide layer patterning steps, (c) Si substrate etching for release, and (d) released μTag devices on wafer surface.

Supplementary Video S2. Time-lapse video of internalization of a round μTag device, as imaged every 30 s over a 30-min period.

Supplementary Video S3. Time-lapse video of internalization of an elongated μTag device, as imaged every 30 s over a 30-min period.



Supplementary Figure S4. Bright field microscopy images of multiple cells with internalized µTag devices.



Supplementary Figure S5. Cross-sectional TEM image of a cell with internalized µTag device.

Supplementary Video S6. Time-lapse video of cell with round µTag device at day 5, as imaged every 5 s over a 3-min period.

Supplementary Video S7. Time-lapse video of cell with elongated µTag device at day 5, as imaged every 5 s over a 3-min period.